According to the EMI shielding structure shown in Figure 11, the vertex of each conical contact protuberance 111 and the EMI shield member 112 makes a point contact. Thus, an increased number of contact protuberances 111 are required to provide a sufficiently low resistance of the electrical connection between the EMI shield member 112 and the ground plane of the printed circuit 110.

A1

In the EMI shielding structure shown in Figure 11, the thickness, as indicated at B, of the EMI shield member 112 adds to an elevation of the remote surface of the EMI shield member 112 from the printed circuit 110. If each contact protuberance 111 has the height A, the final elevation of the remote surface of the EMI shield member 112 can be expressed as the sum (A + B).

Please rewrite the table on page 7, lines 9-11, as follows:

A2

	Ave.	σ_{n-1}	Max.	Min.
Fig. 11	16.95Ω	8.73Ω	28.14Ω	4.80Ω
Figs. 1 & 2	1.04Ω	0.53Ω	1.70Ω	0.47Ω

Please rewrite the paragraph on page 12, lines 3-16, as follows:

A3

In the fifth embodiment, after placing the EMI shield member 11 in desired alignment over the electronic assembly, application of pressure brings each circular aperture defining contact wall 13 into contact with the cylindrical side surface of the second portion 50b of the corresponding one of the contact protuberances 50. After completed, the second portions 50b of contact protuberances 50 close the circular apertures with their tops as high as the remote surface of the EMI shield member 11. Besides, the first portion 50a of each contact protuberance 50 allows the surface of the EMI shield member 11 to rest on the top thereof at around the associated second portion 50b. The cylindrical side surface of the second portion 50b of each